熱伝導接着シート
Thermal Conductive Adhesive Sheet

キュア工程での加圧フリー熱伝導接着

Pressure-free in curing process -- Thermal Conductive Adhesive

コンセプト Concept

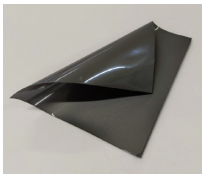
▶ **被着体の凹凸に追従して熱抵抗を低減**
Conform to the surface irregularities of the adhered surface and reduce thermal resistance

▶ **貼合後の厚み均一性を向上**
Improve thickness uniformity after lamination

▶ **ポンプアウトや液だれがなく、良好な作業性**
Good workability without pumping out or liquid dripping

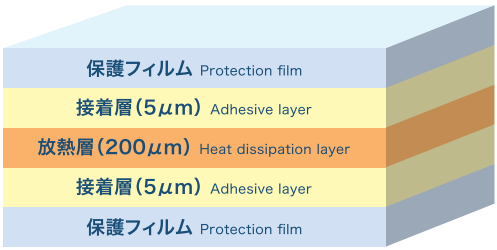
低弾性タイプ（開発品）
Low Elasticity Type（Development product）

▶ **優れた応力緩和性**
Excellent stress relaxation property
弾性率：0.42 Gpa
Elastic Modulus



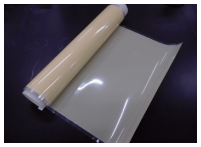
▶ **線膨張係数の異なる材料を貼合**
Bonding materials with different linear expansion coefficient

▶ **熱伝導率2W／mK（定常法）**
Thermal Conductivity（Steady State Method）



高絶縁性タイプ
High Insulation Type

▶ **AC65kV／mmの電気絶縁性（150℃1000h後も特性維持）**
Electrical Insulation: AC65kV/mm (No change after 150℃1000h)



▶ **熱伝導率2W／mK（定常法）**
Thermal Conductivity (Steady State Method)

※放熱層の厚みは調整可能です
The thickness of the heat dissipation layer is adjustable.

※上記数値は代表値であり保証値ではありません。The data are references, not guaranteed values.

アプリケーション Application

▶ **各種装置部品の接合**
Bonding of various equipment parts

▶ **車載用などのパワーデバイス**
Power devices for automobiles, etc.

TOMOEGAWA
株式会社巴川製紙所 TOMOEGAWA CO.,LTD. iCasカンパニー企画室
TEL：03-3516-3405　E-mail：eisui_info@tomoegawa.co.jp